

In series

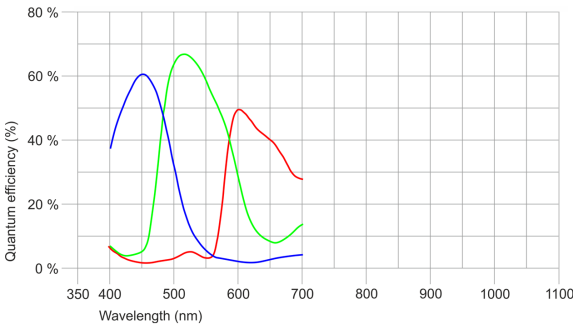
The model is in series and available for the long term.



Specification

Sensor

Sensor type	CMOS Color
Shutter	Rolling shutter
Sensor characteristic	Linear
Pixel Class	12 MP
Resolution	12.00 Mpix
Resolution (h x v)	4000 x 3000 Pixel
Aspect ratio	4:3
ADC	12 bit
Color depth (camera)	12 bit
Optical sensor class	1/1.7"
Optical Size	7.400 mm x 5.550 mm
Optical sensor diagonal	9.25 mm 1/1.7"
Pixel size	1.85 µm
CRA (Chief Ray Angle)	0 °
Manufacturer	Sony
Sensor Model	IMX226CQJ-C
Gain (master/RGB)	16x/16x
AOI horizontal	same frame rate
AOI vertical	same frame rate
AOI image width / step width	256 / 2
AOI image height / step width	2 / 2
AOI position grid (horizontal/vertical)	2 / 2
Binning horizontal	increased frame rate
Binning vertical	increased frame rate
Binning method	Horizontal: mean / Vertical: mean
Binning factor	2x2
Decimation (subsampling) horizontal	-
Decimation (subsampling) vertical	-
Decimation (subsampling) method	M/C automatic



Model

Frame rate freerun mode	10 fps
Frame rate trigger (continuous)	5.3 fps
Frame rate trigger (maximum)	5.3 fps
Exposure time (minimum - maximum)	0.13 ms - 2000 ms
Long exposure (maximum)	30000 ms
Power consumption	1.8 W - 2.9 W
Image memory	128 MB

Ambient conditions

For PCB versions, refer to the separate hints in the respective documentation.

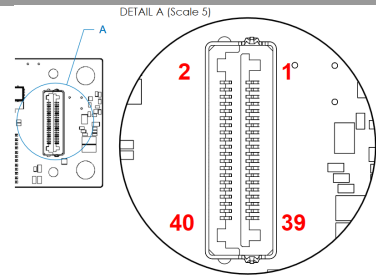
Allowed device temperature during operation	0 °C - 55 °C / 32 °F - 131 °F
Allowed device temperature during storage	-20 °C - 60 °C / -4 °F - 140 °F
Humidity (relative, non-condensing)	20 % - 80 %

Connectors

Interface connector	Samtec LSHM 40-pin
I/O connector	40-pin header (Samtec LSHM-120-L2.5-L-DV-A-S-K-TR)
Power supply	12 V - 24 V

Pin assignment I/O connector

1	Input power supply (VCC) 12-24 V DC ± 10 %
2	Do not connect (for future use)
3	Input power supply (VCC) 12-24 V DC ± 10 %
4	Do not connect (for future use)
5	Ground (GND)
6	Do not connect (for future use)
7	Flash output without optocoupler 3.15 V 8 mA
8	Do not connect (for future use)
9	Trigger input without optocoupler 3.15 V
10	Ground (GND)
11	Do not connect (for future use)
12	Ground (GND)
13	Do not connect (for future use)
14	Do not connect (for future use)
15	I2C SDA (signal data) 3.15 V
16	Do not connect (for future use)
17	I2C SCL (signal clock) 3.15 V
18	Do not connect (for future use)
19	Do not connect (for future use)
20	RJ45 MX0 (-)
21	Do not connect (for future use)
22	RJ45 MX0 (+)
23	General Purpose I/O (GPIO) 2, 3.15 V 8 mA
24	Do not connect (for future use)
25	General Purpose I/O (GPIO) 1, 3.15 V 8 mA
26	RJ45 MX1 (-)
27	Ethernet, LED green, output 3.15 V
28	RJ45 MX1 (+)
29	Power, LED green, output 3.15 V
30	Do not connect (for future use)
31	Power, LED red, output 3.15 V
32	RJ45 MX2 (+)
33	Ethernet, LED red, output 3.15 V
34	RJ45 MX2 (-)
35	Do not connect (for future use)
36	Do not connect (for future use)
37	Do not connect (for future use)
38	RJ45 MX3 (+)
39	Ground (GND)
40	RJ45 MX3 (-)



Design

Lens Mount	No mount
IP code	-
Dimensions H/W/L	84.0 mm x 30.0 mm x 14.3 mm
Mass	25 g
Housing material	-

Features

List of on-camera image pre-processing features.
All features of the table are available via our IDS peak software for image pre-processing on the host computer (sensor model dependent).

Image Acquisition	Freerun	✓
	Software trigger	✓
	Hardware trigger	✓
	Trigger controlled exposure	-
	Denoiser	✓
	Long exposure	✓
	Line scan	-
	Global start	-
Flashing	Flashing	✓
	PWM flashing	✓
Image Adjustments	Auto exposure	✓
	Auto gain	✓
	Auto whitebalance	✓
	Color correction	✓
	Gamma	✓
	LUT	✓
	Mirror/flip	Y
On-board Image Processing	Pixel formats	
	Mono8	
	BayerRG8	
	BayerRG10	
	BayerRG10p	
	BayerRG12	
	BayerRG12p	
	BGR8	
	RGB8	
	BGR10p32	
	RGB10p32	
	Region of interest	✓
	Decimation (FPGA)	✓
	Decimation (Sensor)	
	Binning (FPGA)	✓
	Binning (Sensor)	2x2 Increases frame rate.
Others	IP settings	✓
	Bandwidth management	✓
	Chunks	✓
	Sequencer	-
	PTP	✓
	Firmware update	✓
	1st supported firmware version	2.10